

High Speed SMD Switching Diode

FEATURES

- Fast switching device (t_{rr}<4.0ns)
- Surface mount device type
- Moisture sensitivity level 1
- Matte Tin (Sn) lead finish with Nickel (Ni) underplate
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21







MECHANICAL DATA

- Case: Bend lead SOD-123 small outline plastic package

- Terminal: Matte tin plated, lead free,

solderable per MIL-STD-202, Method 208 guarant - High temperature soldering guaranteed: 260°C/10s

- Polarity: Indicated by cathode band

Weight: 10 ± 0.5 mgMarking Code: T4



SOD-123

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)				
PARAMETER	SYMBOL	VALUE	UNIT	
Power dissipation	P _D	350	mW	
DC blocking voltage	V _R	100	V	
Repetitive peak reverse voltage	V_{RRM}	100	V	
Work peak reverse voltage	V_{RWM}	100	V	
RMS reverse voltage	$V_{R(RMS)}$	70	V	
Repetitive peak forward current	I _{FRM}	300	mA	
Mean forward current	Io	150	mA	
Non-repetitive peak forward surge current @ t=1 ms @ t=10 ms	I _{FSM}	2.0 1.0	А	
Thermal resistance (Junction to Ambient) (Note 1)	$R_{\theta JA}$	357	°C/W	
Junction and storage temperature range	T_J, T_STG	-65 to +150	°C	

PARAI	SYMBOL	MIN	MAX	UNIT	
Forward voltage	I _F =1.0mA		-	0.715	
	I _F =10mA	V _F	-	0.855	V
	I _F =50mA	VF	-	1.000	
	I _F =150mA		-	1.250	
	V _R =20V		-	25	nA
Doverse leekage current	V _R =75V		-	2.5	μA
Reverse leakage current	$V_R=25V$, $T_J=150$ °C	I _R	-	30	μA
	V _R =75V, T _J =150°C		-	50	μA
Junction capacitance	capacitance V _R =0, f=1.0MHz		-	2.0	pF
Reverse recovery time	erse recovery time (Note 2)		-	4.0	ns

Notes: 1. Valid provided that terminals are kept at ambient temperature

Notes: 2. Test Conditions : I_F =10mA, I_R =10mA, R_L =100 Ω , I_{RR} =1mA



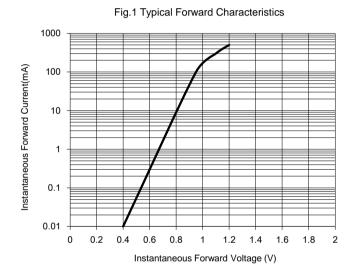
ORDERING INFORMATION				
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
1N4148W-G	RH	G	SOD-123	3K / 7" Reel

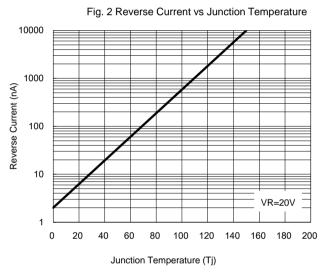
Note: Whole series with green compound

EXAMPLE				
EXAMPLE			PACKING CODE	DESCRIPTION
PART NO.	PART NO.	PACKING CODE	SUFFIX	DESCRIPTION
1N4148W-G RHG	1N4148W-G	RH	G	Green compound

RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)

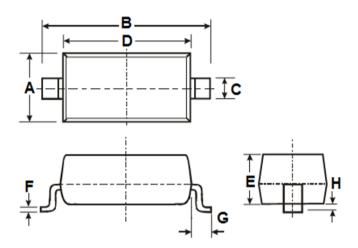






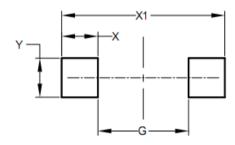
DIMENSIONS

SOD-123

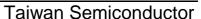


DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min	Max	Min	Max	
Α	1.40	1.80	0.055	0.071	
В	3.55	3.85	0.140	0.152	
С	0.45	0.70	0.018	0.028	
D	2.55	2.85	0.100	0.112	
Е	0.95	1.35	0.037	0.053	
F	0.05	0.15	0.002	0.006	
G	0.50 REF		0.02	REF	
Н	-	0.10	-	0.004	

SUGGESTED PAD LAYOUT



DIM.	Unit (mm)	Unit (inch)	
DIIVI.	Min	Min	
G	2.25	0.089	
Х	0.90	0.035	
X1	4.05	0.159	
Y	0.95	0.037	





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1N4148W-G RHG